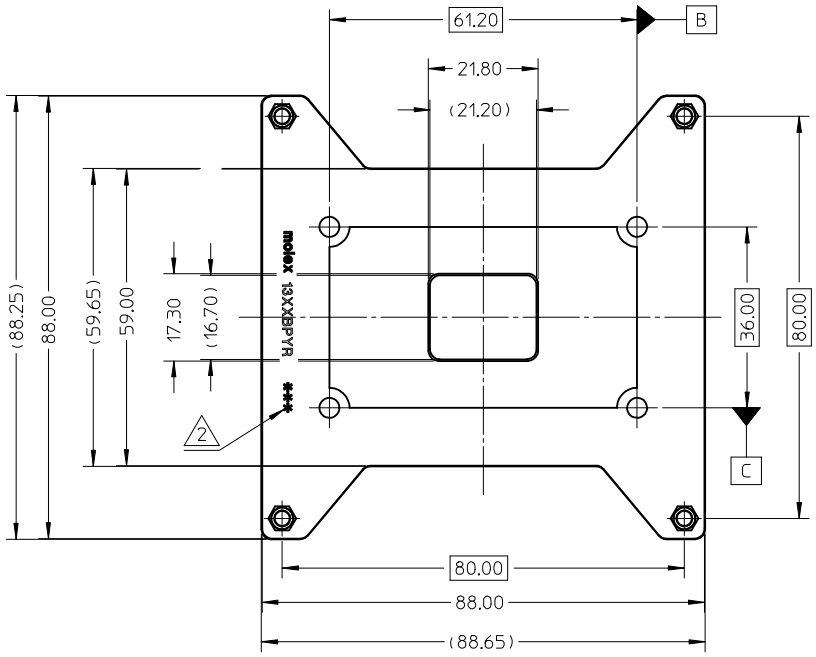
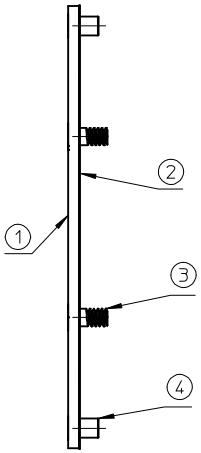
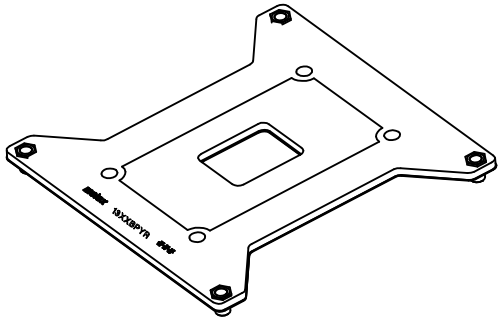






NOTES:
1. MATE WITH LGA13XX ILM ASSEMBLY
   DETAIL REFER TO SD-47593-900
2. DATE CODE
3. THE PARTS 475937000 COMPLIANT TO RoHS
   DIRECTIVE 2002/95/EC AND ELV 2000/53/EC

BILL OF MATERIAL			
ITEM NO	QTY	DESCRIPTION	MATERIAL
	1	BACK PLATE ASSEMBLY FOR SERVER	
1	1	BACK PLATE	STEEL WITH NICKEL PLATING
2	1	BACK PLATE INSULATOR	FORMEX GK-5BK
3	4	BACK PLATE SCREW	STEEL WITH NICKEL PLATING
4	4	BACK PLATE NUT	STEEL

ENTER DESCRIPTION
EC NO: SH2013-0064 2012/10/11
DRWN:YXZHENG
CHKD:
APPR:AYIN 2013/02/04
DESCRIPTION
REV
D

QUALITY SYMBOLS
EA=0
EC=0
EB=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± 0.3	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: YQSUN DATE: 2008/10/13
CHECKED BY: JKACHLIC DATE: 2008/10/13
APPROVED BY: AYIN DATE: 2010/10/22

TITLE
13XX CKT SOCKET
BACK PLATE ASSEMBLY
FOR SERVER APPLICATION

MOLEX INCORPORATED

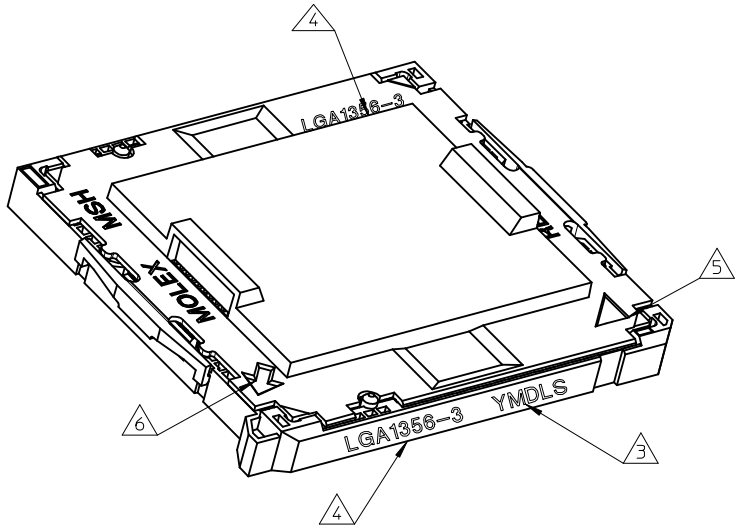
MATERIAL NO. 47593-7000
DOCUMENT NO. SD-47593-700
SHEET NO. 1 OF 1
SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

NOTES:

1. MATERIAL:
   HOUSING: LCP,UL94V-0,COLOR:BLACK.
   TERMINAL:COPPER ALLOY.
   PICK AND PLACE COVER:LCP.
   SOLDER BALL:SEE THE TABLE.
2. PLATING:
   SEE TABLE FOR GOLD ON CONTACT AREA.
   1.27 MICROMETER NICKEL UNDERPLATE.
3. DATE-CODE LOCATION. AND DATE-CODE "YMDLS"
   IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)
4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

5. SOCKET PIN 1 INDICATOR.
6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.
8. PRODUCT PACKAGE PK-47594-003 APPLIES.
9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS
   DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



LGA1356 SOCKET PART NUMBER LIST					PART NAME
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT	
475942001	GENERAL	15u"(0.38um)	LEAD FREE	YES	LGA1356-3(B3)
475942002	GENERAL	30u"(0.76um)			

NEW RELEASED
EC NO: SH2013-0064 2012/09/24
DRWN:YXZHENG
CH'KD:
APPR:AYIN 2013/02/04
DESCRIPTION
REV
1

QUALITY SYMBOLS
FA=0
FC=0
FP=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.25	± ---
0 PLACE	± ---	± ---

ANGULAR ± 1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

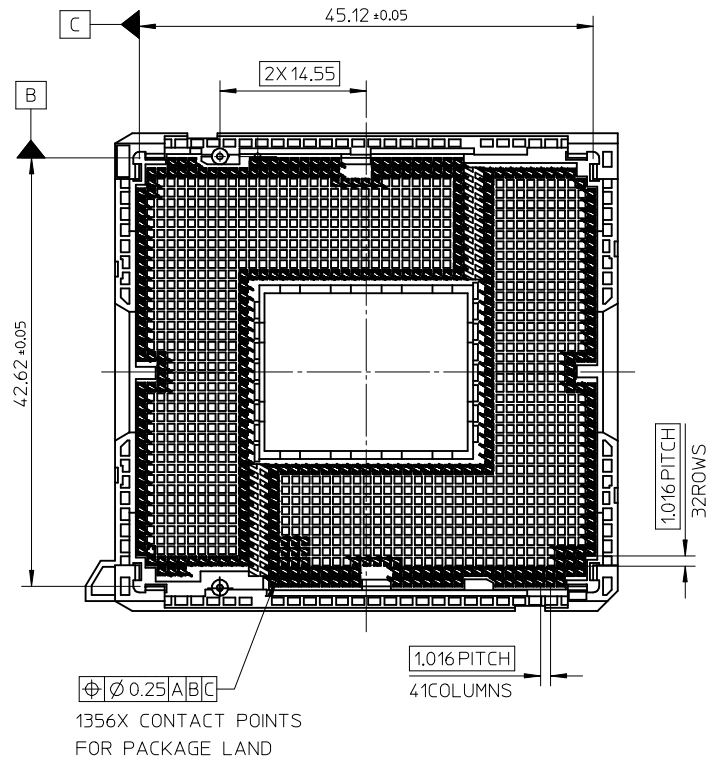
DRAWN BY: YXZHENG DATE: 2012/09/24
CHECKED BY: DATE:
APPROVED BY: AYIN DATE: 2013/02/04

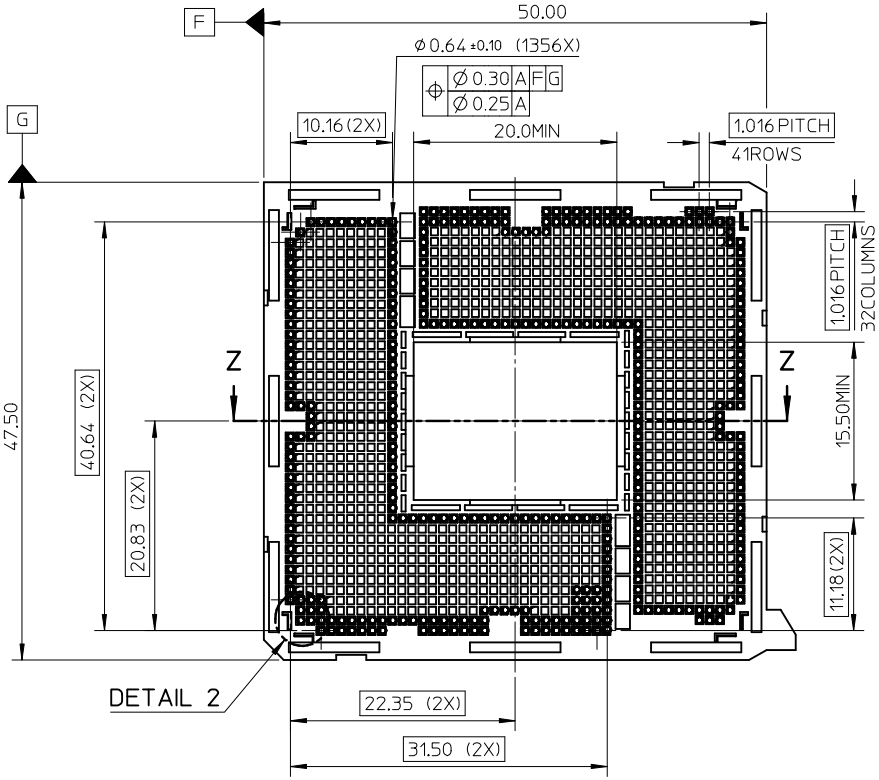
TITLE: LGA1356-3 SOCKET(B3) FULL ASSEMBLY

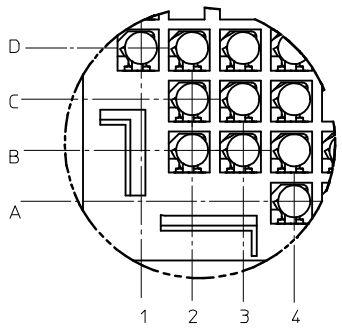
molex

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-47594-200
SHEET NO.: 1 OF 3
SIZE: A3

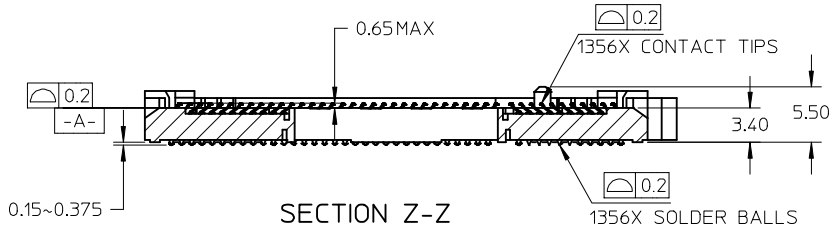
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DETAIL2



SECTION Z-Z

NEW RELEASED	EC NO: SH2013-0064	2012/09/24
DRWN: YXZHENG		
CHKD:		
APPR: AYIN		2013/02/04
DESCRIPTION		
REV	1	

QUALITY SYMBOLS

$\sqrt{E_A}=0$

$\sqrt{E_C}=0$

$\sqrt{E_P}=0$

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.25	± ---
0 PLACE	± ---	± ---

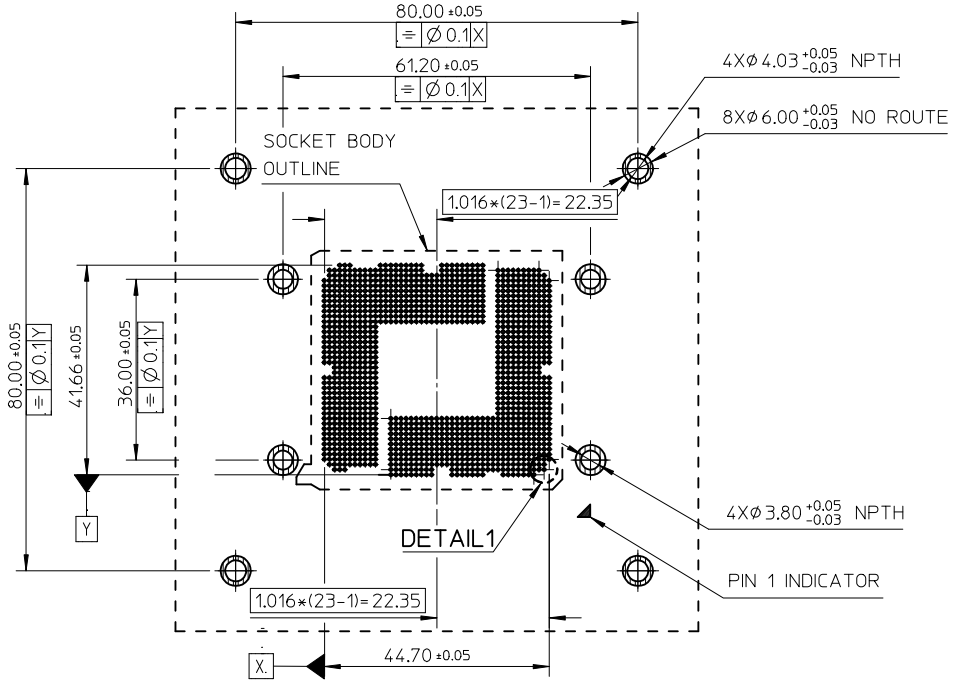
ANGULAR ± 1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	2:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	YXZHENG
DATE	2012/09/24
CHECKED BY	
DATE	
APPROVED BY	AYIN
DATE	2013/02/04
MATERIAL NO.	SEE PAGE 1
TITLE	LGA1356-3 SOCKET(B3) FULL ASSEMBLY
DOCUMENT NO.	SD-47594-200
SHEET NO.	2 OF 3
SIZE	A3

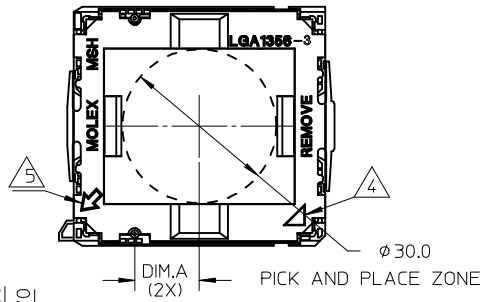
molex

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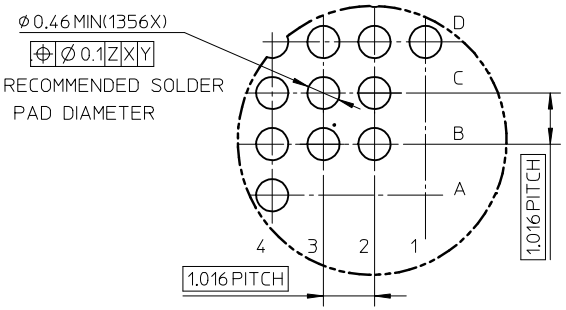
RECOMMEND PCB LAYOUT

THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



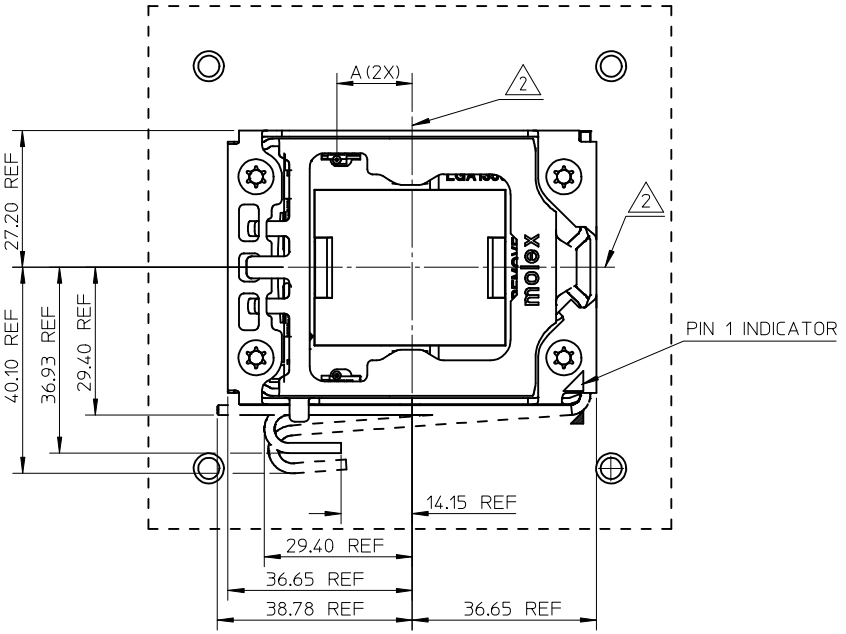
NOTES

1. DATUMN A IS THE PLANE WHICH SOCKET WILL BE SEATED.
2. GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
3. BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
4. SOCKET PIN 1 INDICATOR.
5. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
6. ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.



DETAIL1

SCALE 10:1



SOCKET ON PCB(FOR REFERENCE ONLY)

LOAD PLATE IS NOT LOCKED

NEW RELEASED	EC NO: SH2013-0064	2012/09/24	DRWN: YXZHENG	CHKD:	APPR: AYIN	2013/02/04	DESCRIPTION
1							REV

QUALITY SYMBOLS: F_A=0, F_C=0, F_P=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.25	± ---
0 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: 1:1	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: YXZHENG	DATE: 2012/09/24	TITLE: LGA1356-3 SOCKET(B3) FULL ASSEMBLY	
CHECKED BY	DATE		
APPROVED BY: AYIN	DATE: 2013/02/04	molex	
MATERIAL NO.: SEE PAGE 1		DOCUMENT NO.: SD-47594-200	SHEET NO.: 3 OF 3
SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		